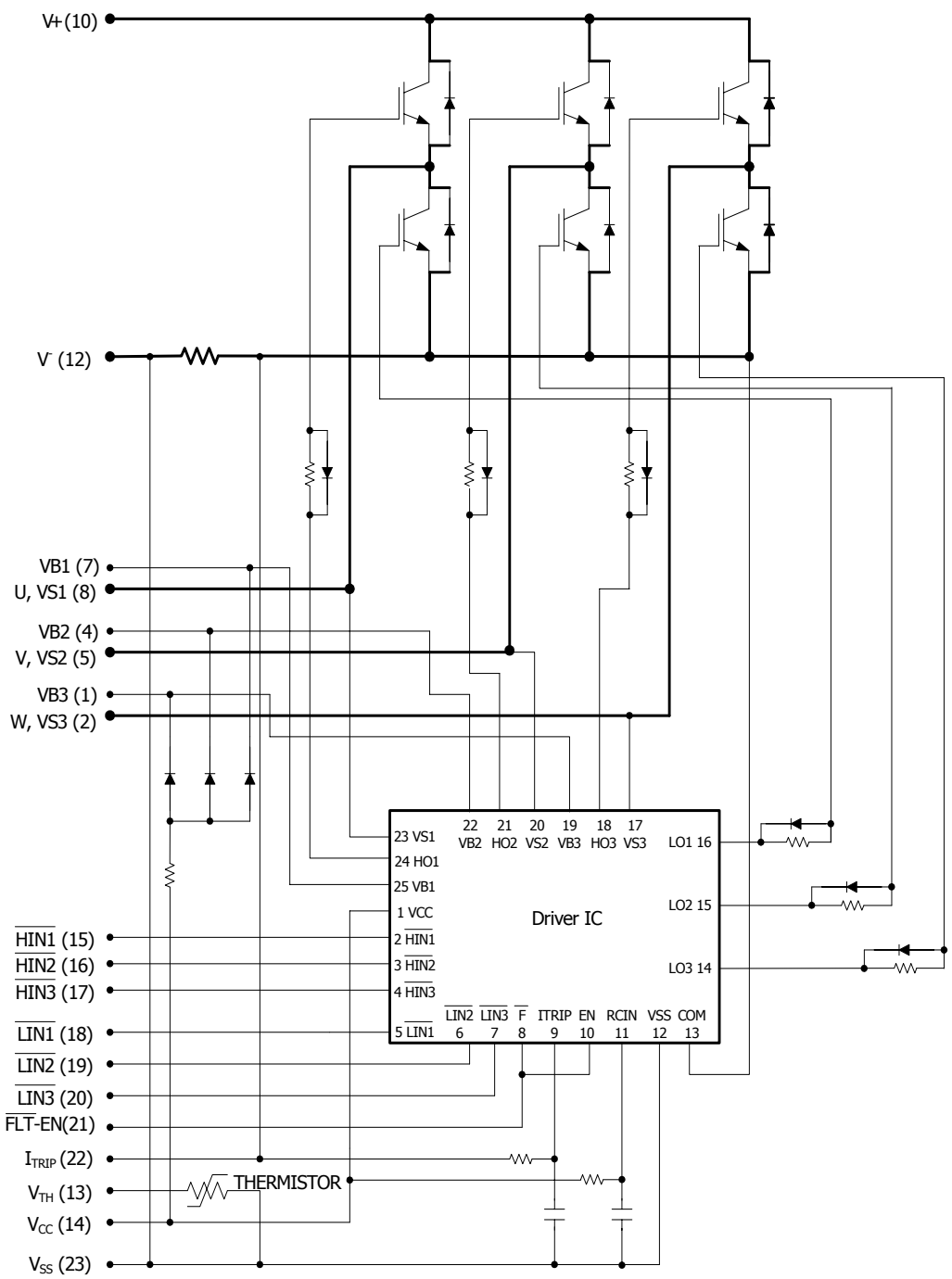
Internal Electrical Schematic - IRAMX16UP60B



Absolute Maximum Ratings (Continued)

All voltages are absolute referenced to COM/I_{TRIP}.

Symbol	Parameter	Min	Max	Units	Conditions
I_{BDF}	Bootstrap Diode Peak Forward Current	---	4.5	A	t_P= 10ms, T_J = 150°C, T_C=100°C
$P_{BR\ Peak}$	Bootstrap Resistor Peak Power (Single Pulse)	---	25.0	W	t_P=100µs, T_C =100°C ESR / ERJ series
$V_{S1,2,3}$	High side floating supply offset voltage	$V_{B1,2,3}$ - 25	$V_{B1,2,3}$ +0.3	V	
$V_{B1,2,3}$	High side floating supply voltage	-0.3	600	V	
V_{CC}	Low Side and logic fixed supply voltage	-0.3	20	V	
V_{IN}, V_{EN}, V_{ITRIP}	Input voltage LIN, HIN, EN, I_{Trip}	-0.3	Lower of (V_{SS}+15V) or V_{CC}+0.3V	V	

Inverter Section Electrical Characteristics @T_J= 25°C

Symbol	Parameter	Min	Typ	Max	Units	Conditions
$V_{(BR)CES}$	Collector-to-Emitter Breakdown Voltage	600	---	---	V	V_{IN}=5V, I_C=250µA
$\Delta V_{(BR)CES}$ / ΔT	Temperature Coeff. Of Breakdown Voltage	---	0.3	---	V/°C	V_{IN}=5V, I_C=1.0mA (25°C - 150°C)
$V_{CE(ON)}$	Collector-to-Emitter Saturation Voltage	---	1.55	1.85	V	I_C=8A, V_{CC}=15V
		---	1.80	2.10		I_C=8A, V_{CC}=15V, T_J=150°C
I_{CES}	Zero Gate Voltage Collector Current	---	5	80	µA	V_{IN}=5V, V^+=600V
		---	165	---		V_{IN}=5V, V^+=600V, T_J=150°C
V_{FM}	Diode Forward Voltage Drop	---	2.0	2.4	V	I_C=8A
		---	1.4	1.9		I_C=8A, T_J=150°C
V_{BDFM}	Bootstrap Diode Forward Voltage Drop	--	--	1.25	V	I_F=1A
		---	---	1.10		I_F=1A, T_J=125°C
R_{BR}	Bootstrap Resistor Value	---	22	---	Ω	T_J=25°C
$\Delta R_{BR}/R_{BR}$	Bootstrap Resistor Tolerance	---	---	±5	%	T_J=25°C
I_{BUS_TRIP}	Current Protection Threshold (positive going)	21	---	28	A	T_J=-40°C to 125°C See Fig. 2

Inverter Section Switching Characteristics @ T_J= 25°C

Symbol	Parameter	Min	Typ	Max	Units	Conditions
E_{ON}	Turn-On Switching Loss	---	315	435	µJ	I_C=8A, V^+=400V V_{CC}=15V, L=2mH Energy losses include "tail" and diode reverse recovery See CT1
E_{OFF}	Turn-Off Switching Loss	---	150	180		
E_{TOT}	Total Switching Loss	---	465	615		
E_{REC}	Diode Reverse Recovery energy	---	30	60		
t_{RR}	Diode Reverse Recovery time	---	70	90	ns	
E_{ON}	Turn-on Switching Loss	---	500	700	µJ	I_C=8A, V^+=400V V_{CC}=15V, L=2mH, T_J=150°C Energy losses include "tail" and diode reverse recovery See CT1
E_{OFF}	Turn-off Switching Loss	---	270	335		
E_{TOT}	Total Switching Loss	---	770	1035		
E_{REC}	Diode Reverse Recovery energy	---	60	100		
t_{RR}	Diode Reverse Recovery time	---	120	150	ns	
Q_G	Turn-On IGBT Gate Charge	---	56	84	nC	I_C=15A, V^+=400V, V_{GE}=15V
RBSOA	Reverse Bias Safe Operating Area	FULL SQUARE				T_J=150°C, I_C=8A, V_P=600V V^+= 450V V_{CC}=+15V to 0V See CT3
SCSOA	Short Circuit Safe Operating Area	10	---	---	µs	T_J=150°C, V_P=600V, V^+= 360V, V_{CC}=+15V to 0V See CT2
I_{CSC}	Short Circuit Collector Current	---	140	---	A	T_J=150°C, V_P=600V, t_{SC}<10µs V^+= 360V, V_{GE}=15V V_{CC}=+15V to 0V See CT2

Recommended Operating Conditions Driver Function

The Input/Output logic timing diagram is shown in Figure 1. For proper operation the device should be used within the recommende conditions. All voltages are absolute referenced to COM/I_{TRIP}. The V_S offset is tested with all supplies biased at 15V differential (Note 3)

Symbol	Definition	Min	Max	Units
$V_{B1,2,3}$	High side floating supply voltage	V_S+12	V_S+20	V
$V_{S1,2,3}$	High side floating supply offset voltage	Note 4	450	
V_{CC}	Low side and logic fixed supply voltage	12	20	V
V_{ITRIP}	I_{TRIP} input voltage	V_{SS}	V_{SS}+5	
V_{IN}	Logic input voltage LIN, HIN	V_{SS}	V_{SS}+4	V
V_{EN}	Logic input voltage EN	V_{SS}	V_{SS}+5	V

Note 3: For more details, see IR21363 data sheet

Note 4: Logic operational for V_s from COM-5V to COM+600V. Logic state held for V_s from COM-5V to COM-V_{BS}. (please refer to DT97-3 for more details)

Static Electrical Characteristics Driver Function

V_{BIAS} (V_{CC}, $V_{BS1,2,3}$)=15V, unless otherwise specified. The V_{IN} and I_{IN} parameters are referenced to COM/I_{TRIP} and are applicable to all six channels. (Note 3)

Symbol	Definition	Min	Typ	Max	Units
V_{INH} , V_{ENH}	Logic "0" input voltage	3.0	---	---	V
V_{INL} , V_{ENL}	Logic "1" input voltage	---	---	0.8	V
V_{CCUV+}, V_{BSUV+}	V_{CC} and V_{BS} supply undervoltage Positive going threshold	10.6	11.1	11.6	V
V_{CCUV-}, V_{BSUV-}	V_{CC} and V_{BS} supply undervoltage Negative going threshold	10.4	10.9	11.4	V
V_{CCUVH}, V_{BSUVH}	V_{CC} and V_{BS} supply undervoltage lock-out hysteresis	---	0.2	---	V
$V_{IN,Clamp}$	Input Clamp Voltage (HIN, LIN, I_{TRIP}) I_{IN}=10µA	4.9	5.2	5.5	V
I_{QBS}	Quiescent V_{BS} supply current V_{IN}=0V	---	---	165	µA
I_{QCC}	Quiescent V_{CC} supply current V_{IN}=0V	---	---	3.35	mA
I_{LK}	Offset Supply Leakage Current	---	---	60	µA
I_{IN+}, I_{EN+}	Input bias current V_{IN}=5V	---	200	300	µA
I_{IN-}, I_{EN-}	Input bias current V_{IN}=0V	---	100	220	µA
I_{TRIP+}	I_{TRIP} bias current V_{ITRIP}=5V	---	30	100	µA
I_{TRIP-}	I_{TRIP} bias current V_{ITRIP}=0V	---	0	1	µA
V(I_{TRIP})	I_{TRIP} threshold Voltage	440	490	540	mV
V(I_{TRIP}, HYS)	I_{TRIP} Input Hysteresis	---	70	---	mV
$R_{ON,FLT}$	Fault Output ON Resistance	---	50	100	ohm

Dynamic Electrical Characteristics

Driver only timing unless otherwise specified.

Symbol	Parameter	Min	Typ	Max	Units	Conditions
T_{ON}	Input to Output propagation turn-on delay time (see fig.11)	---	590	---	ns	V_{CC}=V_{BS}= 15V, I_C=8A, V^+=400V
T_{OFF}	Input to Output propagation turn-off delay time (see fig. 11)	---	660	---	ns	
T_{FLIN}	Input Filter time (HIN, LIN)	100	200	---	ns	V_{IN}=0 & V_{IN}=5V
$T_{BLT-Trip}$	I_{TRIP} Blancking Time	100	150		ns	V_{IN}=0 & V_{IN}=5V
D_T	Dead Time (V_{BS}=V_{DD}=15V)	220	290	360	ns	V_{BS}=V_{CC}=15V
M_T	Matching Propagation Delay Time (On & Off)	---	40	75	ns	V_{CC}= V_{BS}= 15V, external dead time> 400ns
T_{ITrip}	I_{Trip} to six switch to turn-off propagation delay (see fig. 2)	---	---	1.75	µs	V_{CC}=V_{BS}= 15V, I_C=8A, V^+=400V
$T_{FLT-CLR}$	Post I_{Trip} to six switch to turn-off clear time (see fig. 2)	---	7.7	---	ms	T_C = 25°C
		---	6.7	---		T_C = 100°C

Thermal and Mechanical Characteristics

Symbol	Parameter	Min	Typ	Max	Units	Conditions
$R_{th(J-C)}$	Thermal resistance, per IGBT	---	3.5	4.0	°C/W	Flat, greased surface. Heatsink compound thermal conductivity 1W/mK
$R_{th(J-C)}$	Thermal resistance, per Diode	---	5.0	5.5		
$R_{th(C-S)}$	Thermal resistance, C-S	---	0.1	---		
C_D	Creepage Distance	3.2	---	---	mm	See outline Drawings

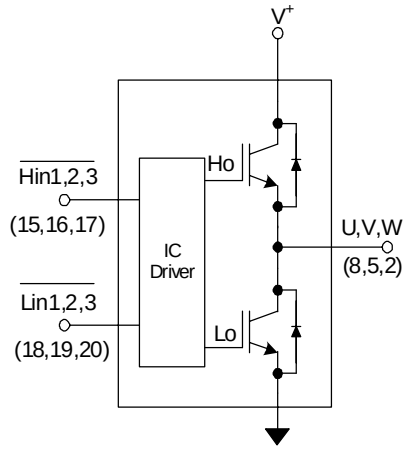
Internal Current Sensing Resistor - Shunt Characteristics

Symbol	Parameter	Min	Typ	Max	Units	Conditions
R_{Shunt}	Resistance	17.9	18.1	18.3	mΩ	T_C = 25°C
T_{Coeff}	Temperature Coefficient	0	---	200	ppm/°C	
P_{Shunt}	Power Dissipation	---	---	3.0	W	-40°C< T_C <100°C
T_{Range}	Temperature Range	-40	---	125	°C	

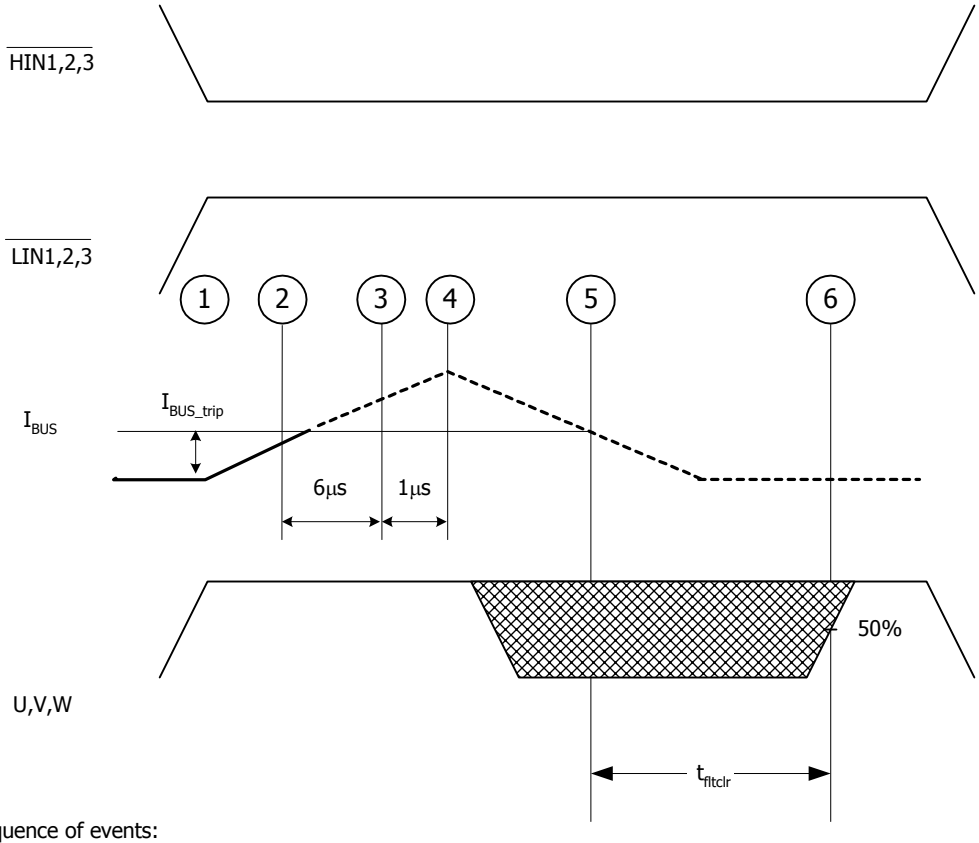
Internal NTC - Thermistor Characteristics

Parameter	Definition	Min	Typ	Max	Units	Conditions
R_{25}	Resistance	97	100	103	kΩ	T_C = 25°C
R_{125}	Resistance	2.25	2.52	2.80	kΩ	T_C = 125°C
B	B-constant (25-50°C)	4165	4250	4335	k	$R_2 = R_1 e^{[B(1/T2 - 1/T1)]}$
Temperature Range		-40		125	°C	
Typ. Dissipation constant			1		mW/°C	T_C = 25°C

Input-Output Logic Level Table



FLT- EN	I_{TRIP}	$\overline{HIN1,2,3}$	$\overline{LIN1,2,3}$	U,V,W
1	0	0	1	V^+
1	0	1	0	0
1	0	1	1	Off
1	1	X	X	Off
0	X	X	X	Off



Sequence of events:
1-2) Current begins to rise
2) Current reaches I_{BUS_Trip} level
2-3) Current is higher than I_{BUS_Trip} for at least 6µs. This value is the worst-case condition with very low over-current. In case of high current (short circuit), the actual delay will be smaller.
3-4) Delay between driver identification of over-current condition and disabling of all outputs
4) Current starts decreasing, eventually reaching 0
5) Current goes below I_{BUS_trip}, the driver starts its auto-reset sequence
6) Driver is automatically reset and normal operation can resume (over-current condition must be removed by the time the drivers automatically resets itself)

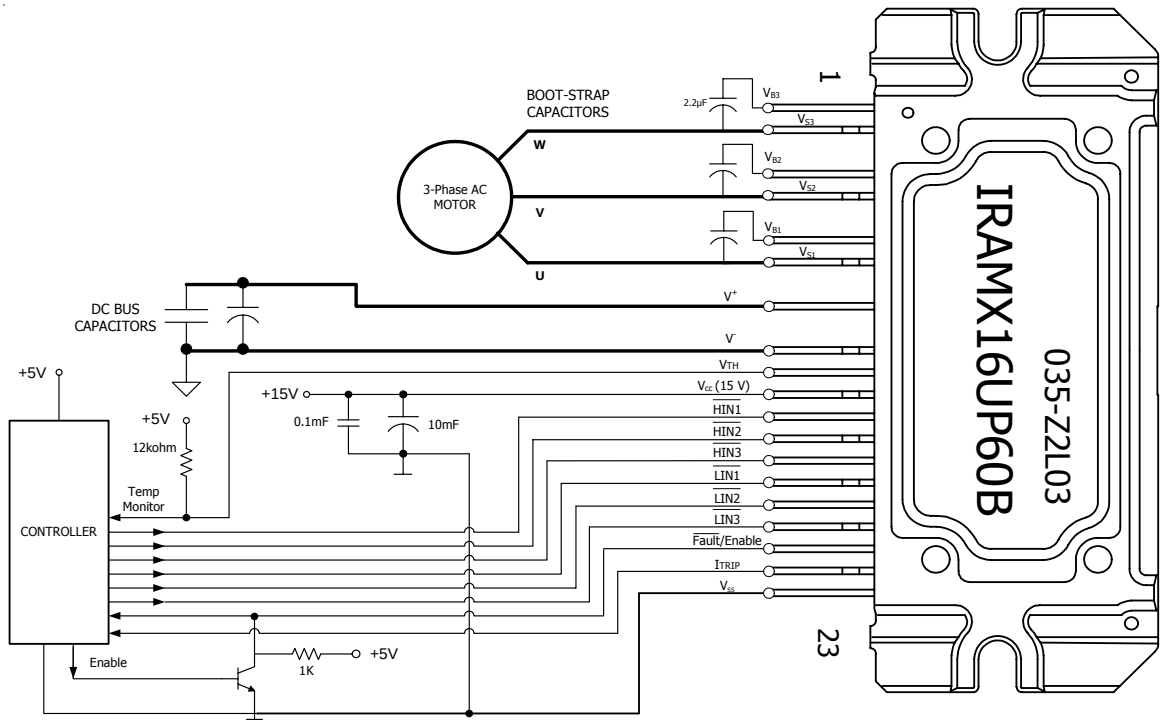
Figure 2. I_{Trip} Timing Waveform

Note 5: The shaded area indicates that both high-side and low-side switches are off and therefore the half-bridge output voltage would be determined by the direction of current flow in the load.

Module Pin-Out Description

Pin	Name	Description
1	V_{B3}	High Side Floating Supply Voltage 3
2	W,V_{S3}	Output 3 - High Side Floating Supply Offset Voltage
3	NA	none
4	V_{B2}	High Side Floating Supply voltage 2
5	V,V_{S2}	Output 2 - High Side Floating Supply Offset Voltage
6	NA	none
7	V_{B1}	High Side Floating Supply voltage 1
8	U, V_{S1}	Output 1 - High Side Floating Supply Offset Voltage
9	NA	none
10	V^+	Positive Bus Input Voltage
11	NA	none
12	V^-	Negative Bus Input Voltage
13	V_{TH}	Temperature Feedback
14	V_{CC}	+15V Main Supply
15	$\overline{H_{IN1}}$	Logic Input High Side Gate Driver - Phase 1
16	$\overline{H_{IN2}}$	Logic Input High Side Gate Driver - Phase 2
17	$\overline{H_{IN3}}$	Logic Input High Side Gate Driver - Phase 3
18	$\overline{L_{IN1}}$	Logic Input Low Side Gate Driver - Phase 1
19	$\overline{L_{IN2}}$	Logic Input Low Side Gate Driver - Phase 2
20	$\overline{L_{IN3}}$	Logic Input Low Side Gate Driver - Phase 3
21	$\overline{FAULT}$	Fault Indicator
22	I_{TRIP}	Current Sense and Itrip Pin
23	V_{SS}	Negative Main Supply

Typical Application Connection IRAMX16UP60B



1. Electrolytic bus capacitors should be mounted as close to the module bus terminals as possible to reduce ringing and EMI problems. Additional high frequency ceramic capacitor mounted close to the module pins will further improve performance.

2. In order to provide good decoupling between V_{CC}-V_{SS} and $V_{B1,2,3}$-$V_{S1,2,3}$ terminals, the capacitors shown connected between these terminals should be located very close to the module pins. Additional high frequency capacitors, typically 0.1µF, are strongly recommended.

3. Value of the boot-strap capacitors depends upon the switching frequency. Their selection should be made based on IR design tip DN 98-2a, application note AN-1044 or Figure 9. Bootstrap capacitor value must be selected to limit the power dissipation of the internal resistor in series with the V_{CC}. (see maximum ratings Table on page 3).

4. Current sense signal can be obtained from pin 20 and pin 23. Care should be taken to avoid having inverter current flowing through pin 22 to mantain required current measurement accuracy

5. After approx. 8ms the FAULT is reset. (see Dynamic Characteristics Table on page 5).

6. PWM generator must be disabled within Fault duration to garantee shutdown of the system, overcurrent condition must be cleared before resuming operation.

7. Fault/Enable pin must be pulled-up to +5V.

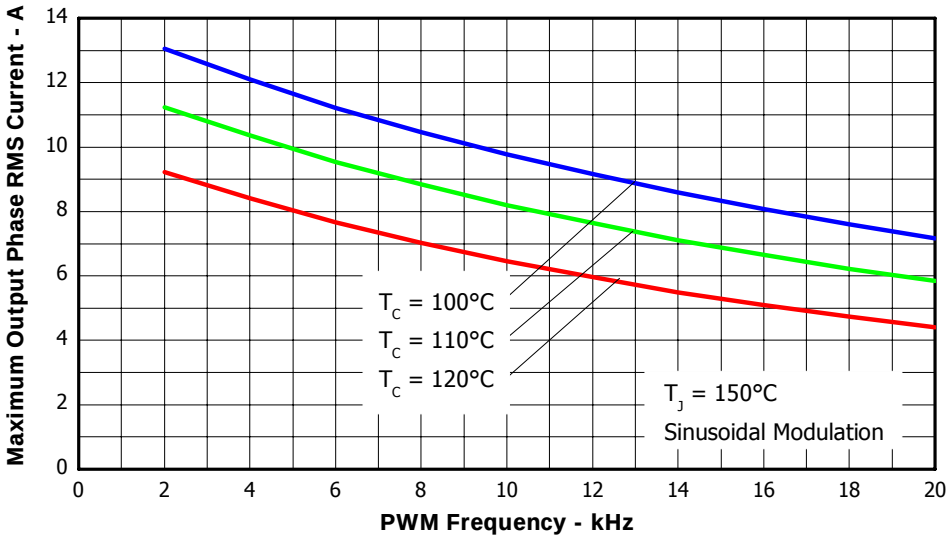


Figure 3. Maximum Sinusoidal Phase Current vs. PWM Switching Frequency
V^+=400V , T_J=150°C, Modulation Depth=0.8, PF=0.6

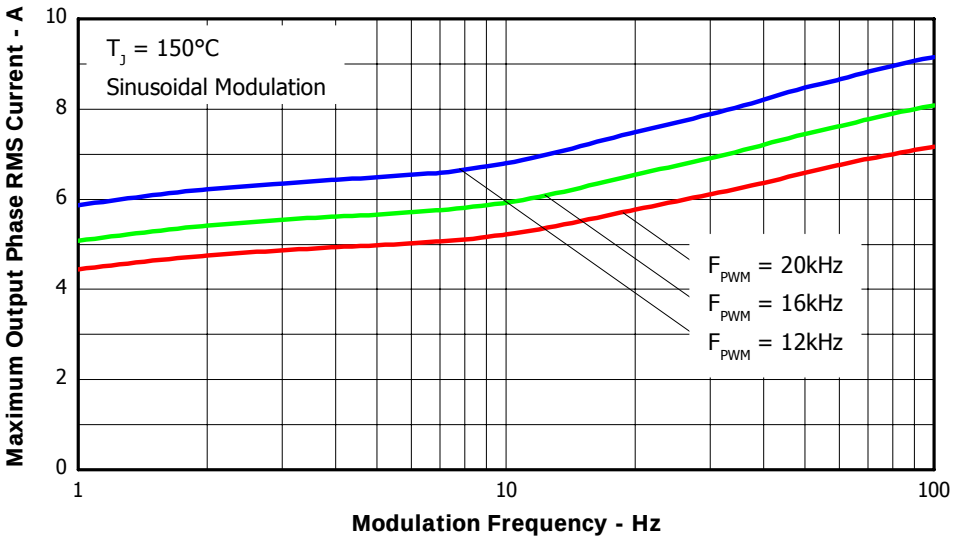


Figure 4. Maximum Sinusoidal Phase Current vs. Modulation Frequency
V^+=400V, T_J=150°C, T_C=100°C, Modulation Depth=0.8, PF=0.6

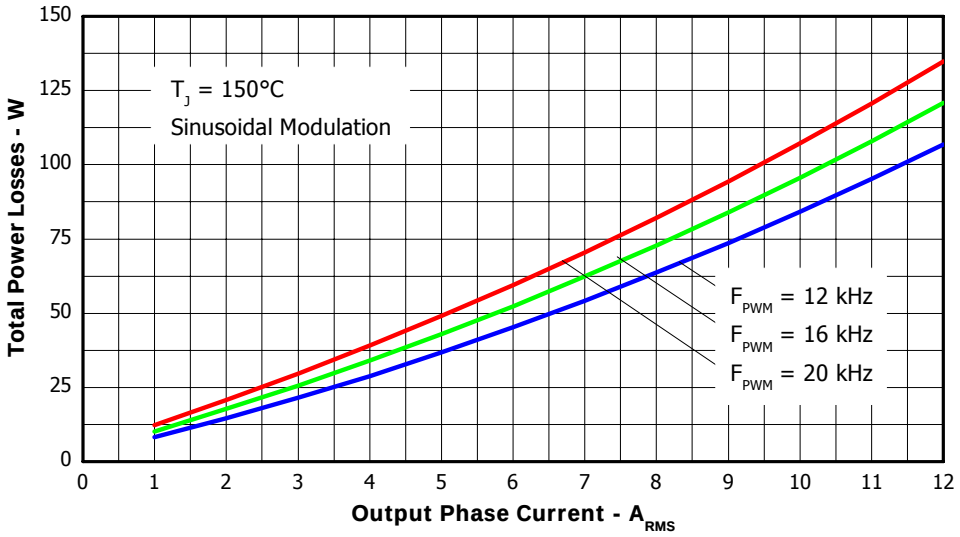


Figure 5. Total Power Losses vs. PWM Switching Frequency, Sinusoidal modulation
V^+=400V , T_J=150°C, Modulation Depth=0.8, PF=0.6

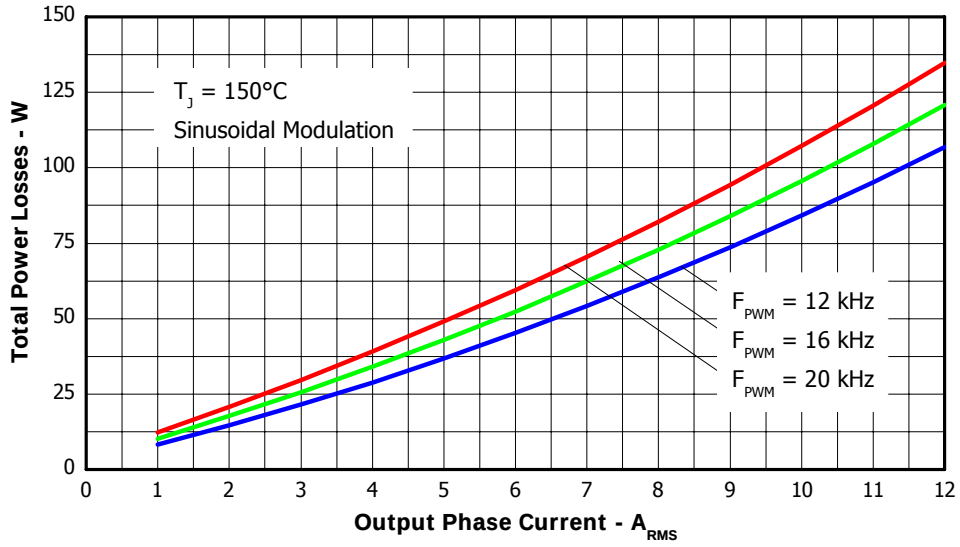


Figure 6. Total Power Losses vs. Output Phase Current, Sinusoidal modulation
V_{BUS}=400V , T_J=150°C, Modulation Depth=0.8, PF=0.6

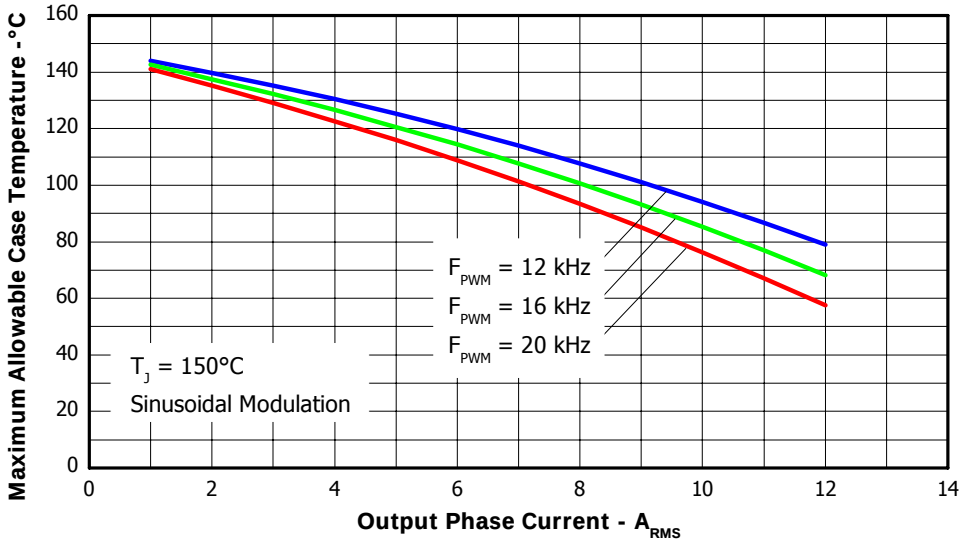


Figure 7. Maximum Allowable Case temperature vs. Output RMS Current per Phase

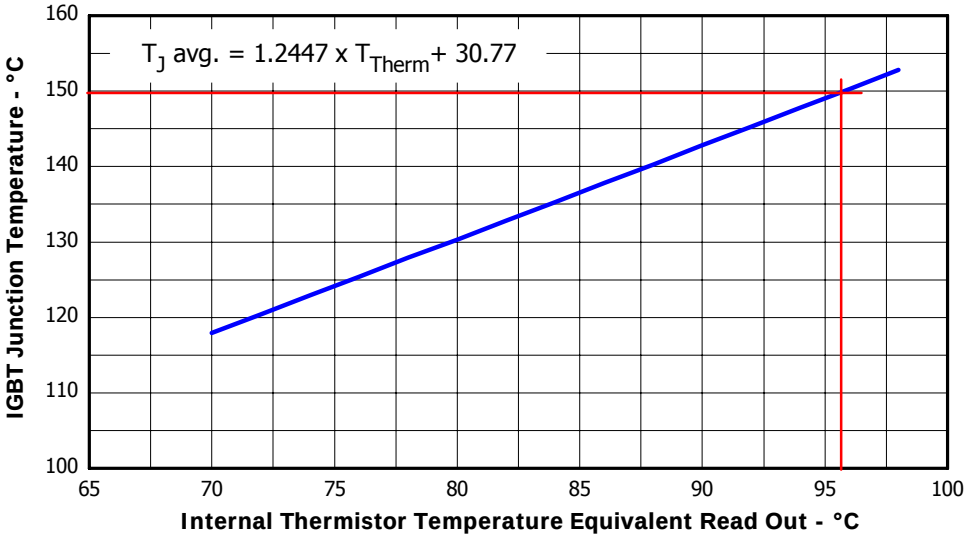
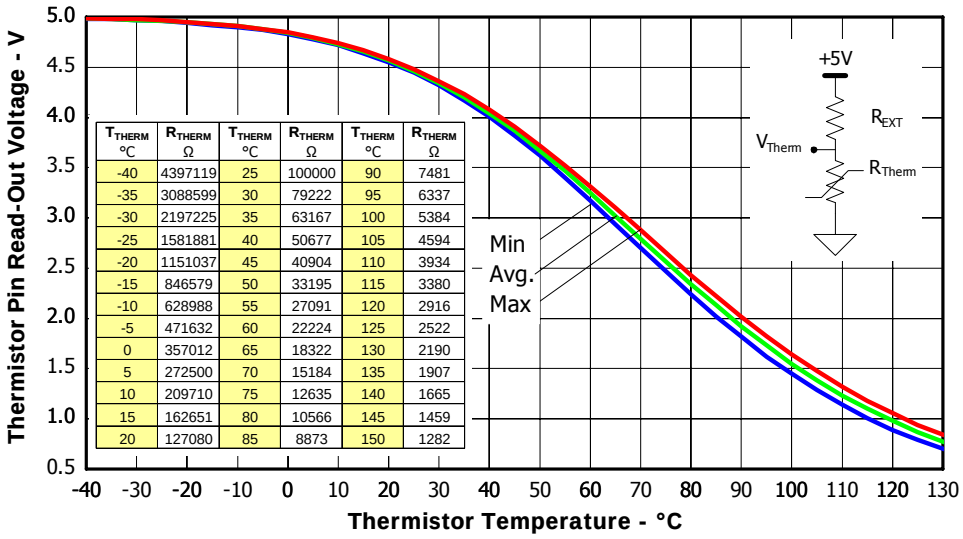


Figure 8. Estimated Maximum IGBT Junction Temperature vs. Thermistor Temperature



T_{THERM} °C	R_{THERM} Ω	T_{THERM} °C	R_{THERM} Ω	T_{THERM} °C	R_{THERM} Ω
-40	4397119	25	100000	90	7481
-35	3088599	30	79222	95	6337
-30	2197225	35	63167	100	5384
-25	1581881	40	50677	105	4594
-20	1151037	45	40904	110	3934
-15	846579	50	33195	115	3380
-10	628988	55	27091	120	2916
-5	471632	60	22224	125	2522
0	357012	65	18322	130	2190
5	272500	70	15184	135	1907
10	209710	75	12635	140	1665
15	162651	80	10566	145	1459
20	127080	85	8873	150	1282

Figure 9. Thermistor Readout vs. Temperature (12kohm pull-up resistor, 5V) and Nominal Thermistor Resistance values vs. Temperature Table.

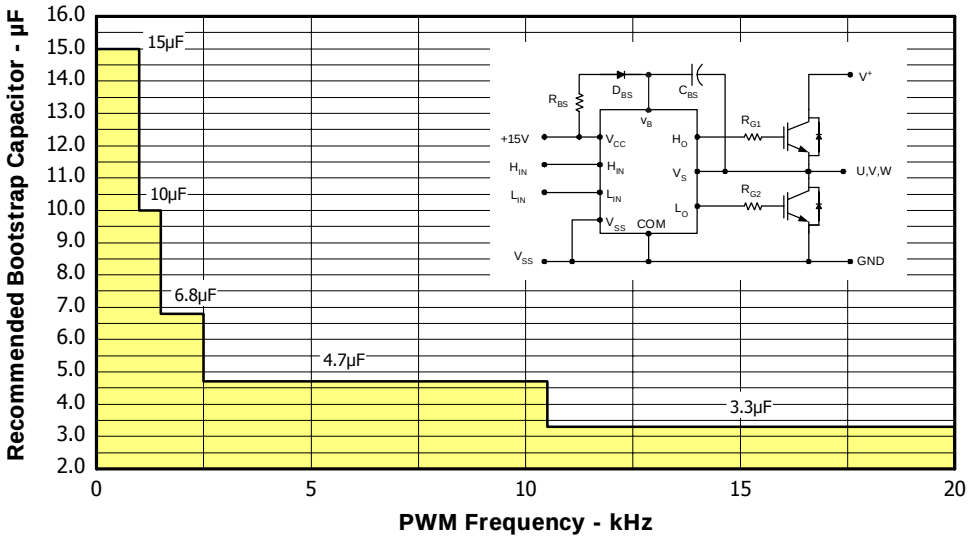


Figure 10. Recommended Bootstrap Capacitor Value vs. Switching Frequency

Figure 11. Switching Parameter Definitions

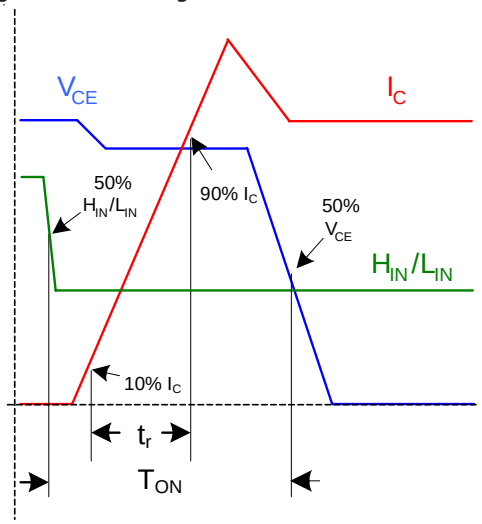


Figure 11a. Input to Output Propagation turn-on Delay Time

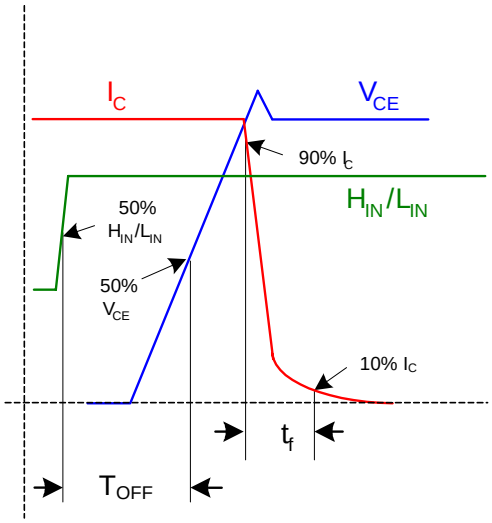


Figure 11b. Input to Output Propagation turn-off Delay Time

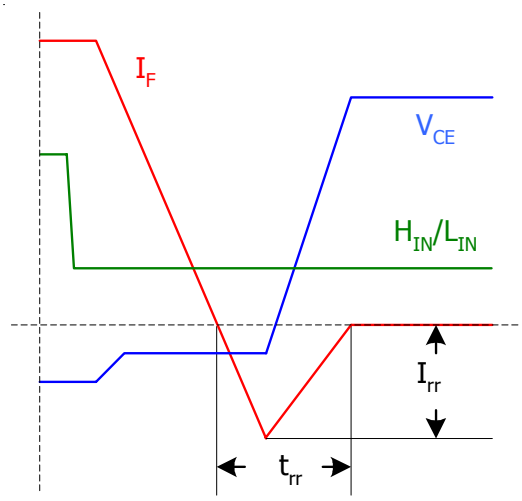


Figure 11c. Diode Reverse Recovery

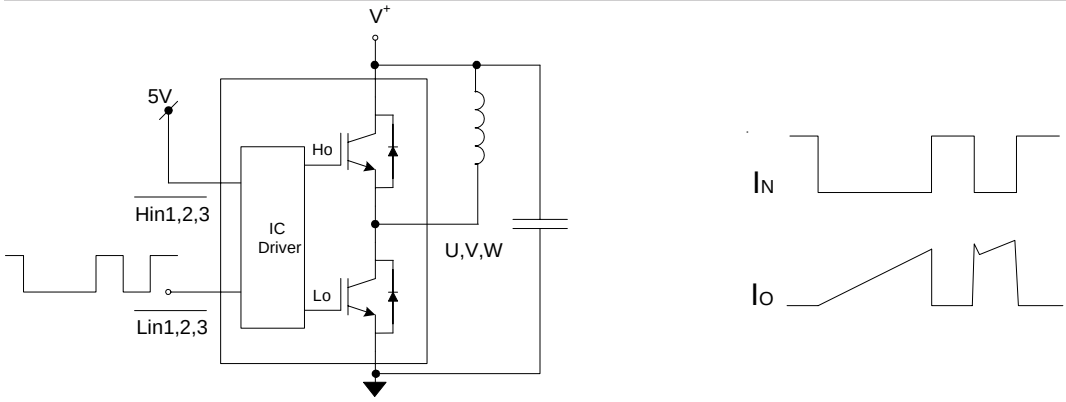


Figure CT1. Switching Loss Circuit

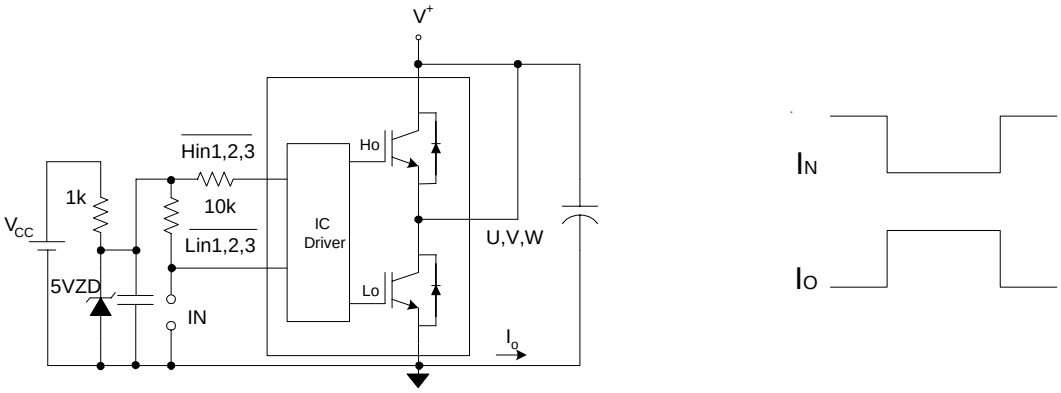


Figure CT2. S.C.SOA Circuit

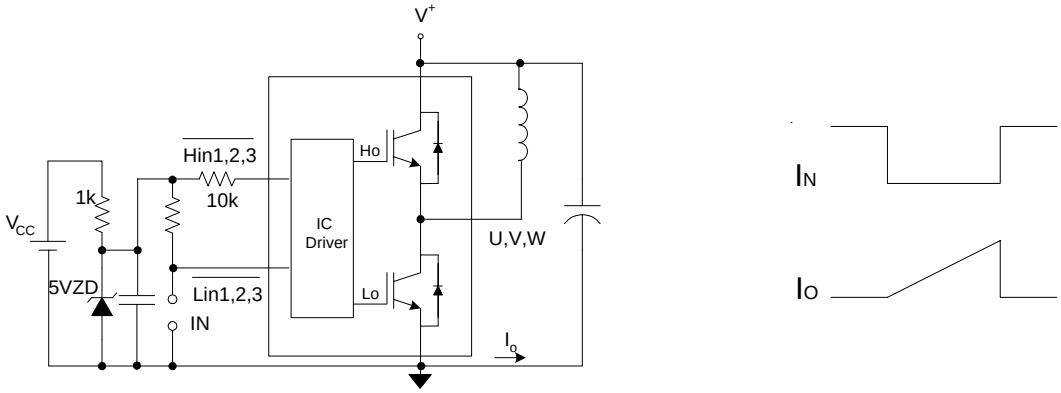
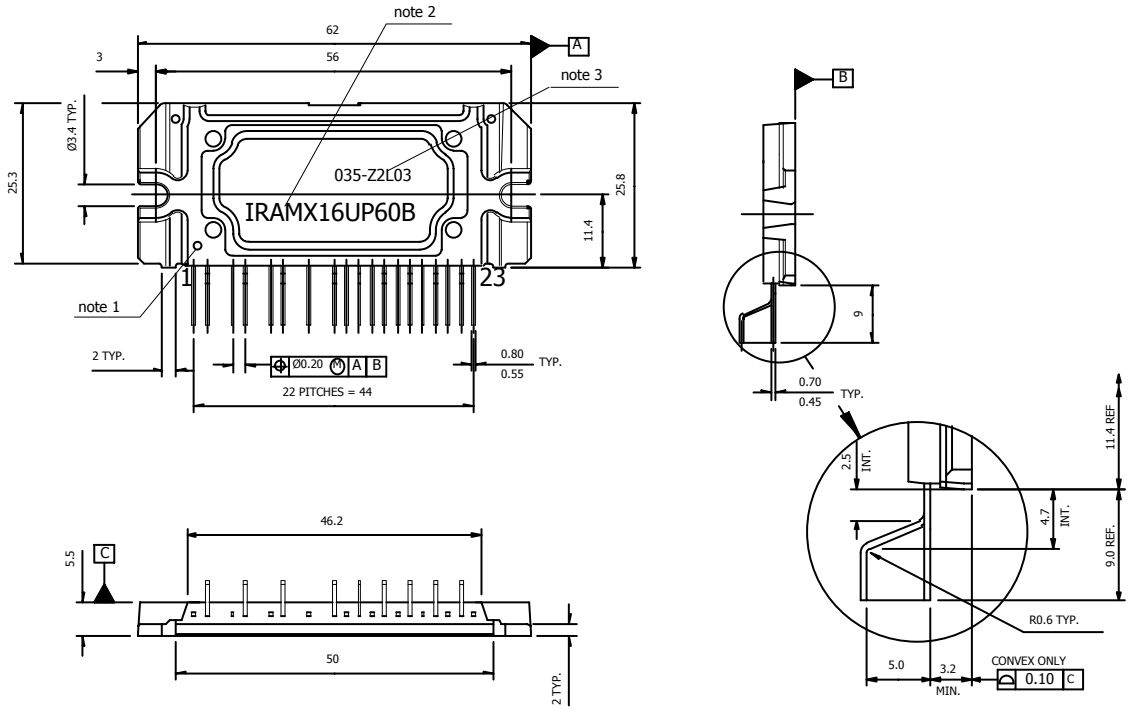


Figure CT3. R.B.SOA Circuit

Package Outline IRAMX16UP60B



Notes:

Dimensions in mm

1- Marking for pin 1 identification

2- Product Part Number

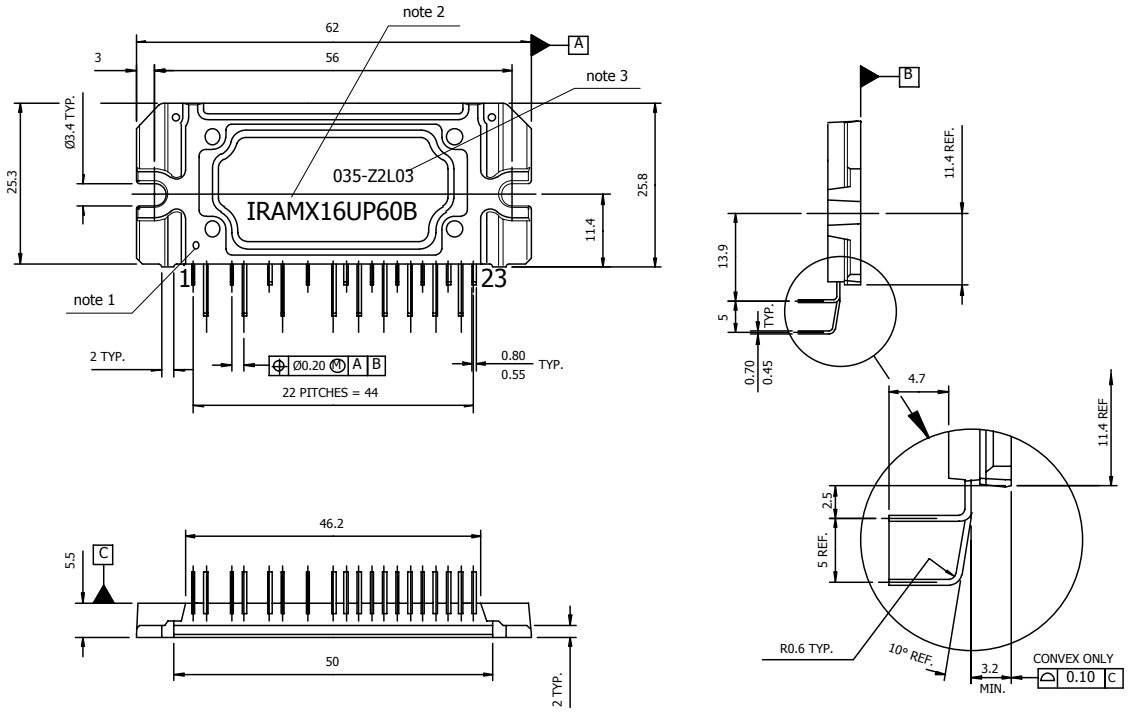
3- Lot and Date code marking

4- Convex only 0.15mm typical

5- Tollerances ±0.5mm, unless otherwise stated

For mounting instruction see AN-1049

Package Outline IRAMX16UP60B-2



Notes:

Dimensions in mm

1- Marking for pin 1 identification

2- Product Part Number

3- Lot and Date code marking

4- Convex only 0.15mm typical

5- Tollerances ±0.5mm, unless otherwise stated

For mounting instruction see AN-1049

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